

8755 W. Higgins Road Suite 500 Chicago, Illinois USA 60631

Sep 30th, 2022

RE: PCN # ESU270-84 - SOD323 additional backend location approval

To our valued customers,

Littelf use would like to notify you of an additional approved backend location for SOD323 TVS Diode Array (SPA® Diodes) products. This additional backend factory in China is fully approved for all assembly, test, and packing operations. There are no changes to fit, form, and function of the finished products.

Qualification efforts are complete, and the new factory is ramping for shipments.

Products Affected:

Affected Part Numbers				
SD05-01FTG	SD15-01FTG	SD36-01FTG		
SD05C-01FTG	SD15C-01FTG	SD36C-01FTG		
SD12-01FTG	SD24-01FTG	SP4020-01FTG		
SD12C-01FTG	SD24C-01FTG	SP4020-01FTG-C		
SP4021-01FTG	SP4022-01FTG	SP4023-01FTG		
SP4021-01FTG-C	SP4022-01FTG-C	SP4023-01FTG-C		
SP4024-01FTG	SP4024-01FTG-C			

The affected products have been fully qualified in accordance with established performance and reliability criteria. The attached pages summarize the qualification results. Full qualification data and/or samples will be available upon request.

Form, fit, function changes: None Part number changes: None

Effective date: Dec 31st 2022, or sooner

Replacement products: N/A

Last time buy: N/A

This notification is for your information and acknowledgement. If you have any other questions or concerns, please contact Sophia Hu, Assistant Product Manager.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Sophia Hu
TVS Diode Array Assistant Product Manager
Semiconductor Business Unit, Wuxi, China
+86 510 85277701 - 7653
shu@littelfuse.com

PCN#:		Contact Information	
ESU270-84 Date: Sep 30th, 2022		Name: Sophia Hu	
Decided Idea (Cartan		Title: Assistant Product Manager	
Product Identification :		Phone #: +86 13771377277	
SOD323 additional backend location approval		Fax#: N/A	
Implementation Date for Change:		E-mail: shu@littelfuse.com	
Dec 31 st , 2022 or sooner			
Category of Change:	Description of Char	nge:	
☐ Assembly Process		backend assembly, test, and packing location for	
☐ Data Sheet	products.	no changes to fit, form & function of the finished	
☐ Technology	products.		
☐ Discontinuance/Obsolescence			
☐ Equipment			
Manufacturing Site			
■ Raw Material			
☐ Testing			
☐ Fabrication Process			
Other:			
Important Dates:			
☐ Qualification Samples Available: Up	on request	☐ Last Time Buy:	
☑ Final Qualification Data Available: Upon request			
☐ Date of Final Product Shipment:			
Method of Distinguishing Changed Pr	oduct		
☑ Product Mark, See (8.0) in the succe	eding PCN report for	details	
☐ Date Code,			
☐ Other,			
Demonstrated or Anticipated Impact of	on Form, Fit, Function	on or Reliability:	
N/A			
LF Qualification Plan/Results:			
Yes			
Customer Acknowledgement of Recei	pt: Littelfuse requests yo	u acknowledge receipt of this PCN. In your acknowledgement, you can	
grant approval or request additional information. Littelfuse will assume the change is acceptable if no acknowledgement is received within 30 days			
of this notice. Lack of any additional response within 90 days of PCN issuance further constitutes acceptance of the change.			



Prepared By: Light Hsieh-Product Engineering Supervisor,

Raider Chen-Product Engineer, Sophia Hu- Assistant Product Manager

Date : 2022/9/22

Device : Please refer to 2.1.

Revision : A

1.0 Objective:

Qualify alternative assembly supplier for SOD323 package type products. Summarize the physical items, electrical characteristics and reliability result of qualification lots.

2.0 Applicable Devices:

2.1 **Product name:**

Part Numbers				
SD05-01FTG	SD15-01FTG	SD36-01FTG		
SD05C-01FTG	SD15C-01FTG	SD36C-01FTG		
SD12-01FTG	SD24-01FTG	SP4020-01FTG		
SD12C-01FTG	SD24C-01FTG	SP4020-01FTG-C		
SP4021-01FTG	SP4022-01FTG	SP4023-01FTG		
SP4021-01FTG-C	SP4022-01FTG-C	SP4023-01FTG-C		
SP4024-01FTG	SP4024-01FTG-C			

3.0 Assembly, Process & Material Differences/Changes:

3.1 Assembly Changes

No change of assemble process.

3.2 Process Changes

No change of process method.

3.3 Material Change

Raw materials					
Item	Original	New	Change or not		
Lead frame	Alloy42	Alloy42	No		
Die Attach Material	84-1LMISR4/DA-5880	84-1LMISR4	Yes		
Wire	Gold	Gold	No		
Mold Compound	EME-500/G600/ELER- 8-100HFE	EMG-400/G600	Yes		
Plating	Matte Tin	Matte Tin	No		

4.0 Packing Method

No change of packing method.

5.0 Physical Differences/Changes:

No change of packing method.

6.0 Reliability Test Results Summary:

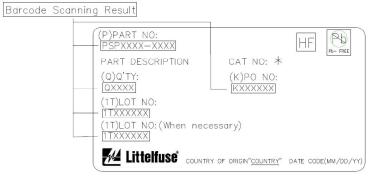
Test Items	Condition	S/S	Results	ETR#
Pre-conditioning (PC)	JESD22-A113	308 each lot	0/924	
DC Blocking (HTRB)	Bias = VRWM, Ta = 150°C, Duration = 1008 Hours	77 each lot	0/231	
Temperature Cycle (TC)	I TOOU Cycles	77 each lot	0/231	474000
Temperature/Humidity (H3TRB)	Ta = 85°C, 85% RH, Bias = VRWM, Duration = 1008 Hours	77 each lot	0/231	174600 174604 174614
Autoclave (AC)	Ta = 121°C, 100%RH, 2ATM, Duration = 96 Hours	77 each lot	0/231	174014
Resistance to Solder Heat (RSH)	260°C, 10 sec, M-2031	10 each lot	0/30	
Moisture Sensitivity Level (MSL)	Per Jedec J-STD-020D Level 1	308 each lot	0/924	
Solderability (SD)	ANSI-J-STD-002	10 each lot	0/30	

7.0 Electrical Characteristic Summary:

Electrical performances were comparable and characterization data is available upon request.

8.0 Changed Part Identification:

Suppliers were qualified by Littelfuse and product can be identified by CAT NO on the label.



9.0 Approvals:

Sophia Hu **SPA Assistant Product Manager** Littelfuse, Wuxi

Light Hsieh SPA Product Engineering Supervisor SPA Product Engineer Littelfuse, HsinChu

Raider Chen Littelfuse, HsinChu